

Conductive Compounds Grades

| Grade | Polymer Type | Typical MFI (dg/min) | Surface Resistivity (Ω^2) | Flexural Modulus (MPa) | Tensile Strength (MPa) | Izod Impact (KJm ⁻²) | Process | | | | Typical Use | Comments | | |
|----------|--------------|---------------------------------|------------------------------------|------------------------|------------------------|----------------------------------|------------|---------------|-------|-----------|-------------|--|---|--|
| | | | | | | | Blown Film | Blow Moulding | Sheet | Extrusion | | | | |
| PEB4055 | lIdPE | 7.5(MFI ₁₀ @190C) | <10 ⁴ | 300 | 12.3 | 66.0 | ● | | ● | ● | | Conductive PE Film >25µm | Low resistivity lIdPE compound developed for film and sheeting | |
| PECB8017 | hdPE | 5.0(MFI _{21.6} @190C) | <10 ⁴ | 1203 | 13.0 | 8.0 | | ● | ● | ● | ● | Sheet and Profile Extrusion | Low resistivity hdPE compound developed for sheet and Profile Extrusion | |
| PECB8024 | ldPE | 38.0(MFI _{21.6} @190C) | <10 ⁵ | 286 | 9.0 | 45.0 | | | | | ● | Injection moulded parts, inc large mouldings | High impact,static dissipative grade, ideal for static safe packaging | |
| PPCB8050 | PP | 35.0(MFI _{5.0} @230C) | <10 ⁵ | 918 | 17.8 | 41.0 | ● | ● | ● | ● | ● | Injection moulded with integral subparts | Low resistivity PP compound with excellent processing properties | |
| PPCB8060 | PP | 69.0(MFI _{5.0} @230C) | <10 ³ | 771 | 15.6 | 41.3 | ● | | | | ● | Large and complex Injection Mouldings with integral subparts | Low resistivity PP compound with excellent high flow properties | |
| PPCB8514 | PP | 9.0(MFI _{5.0} @230C) | <10 ⁴ | 1382 | 17.1 | 23.1 | ● | | ● | ● | | Film and Sheet extrusion | Low resistivity PP compound with good extrusion characteristics | |
| PSCB8101 | PS | 30.0(MFI _{21.6} @200C) | <10 ⁴ | 2993 | 19.7 | 2.2 | | | ● | ● | ● | Sheet extrusion, injection moulding and thermoforming | Low resistivity PS compound with excellent high flow properties | |
| PSCB8018 | PS | 20.0(MFI _{10.0} @200C) | <10 ⁴ | 1600 | 18.8 | 9.0 | | | ● | ● | ● | Sheet extrusion, injection moulding and thermoforming | Low resistivity PS compound with excellent high flow properties | |
| PACB252 | ABS | 26.0(MFI _{21.6} @200C) | <10 ⁵ | 1737 | 10.9 | 3.4 | | | ● | ● | ● | Sheet extrusion and injection moulding for electronic components | Low resistivity grade with excellent melt strength and flow properties, ideal for extrusion | |
| PUCB112 | PU | 13.1(MFI _{10.0} @190C) | <10 ³ | 33 | 12.0 (yield) | No Break | | | | | ● | ● | Low resistivity flexible mouldings and extrusion profiles | Can be diluted with other polymers to give disappative properties. 79 Shore A hardness |